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(12) **United States Design Patent**  
**Okawa et al.**

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(54) **PRESSURE SENSOR PACKAGE**

(56) **References Cited**

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(\*\*) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (9) Cl.** ..... **10-04**

(52) **U.S. Cl.**  
USPC ..... **D10/85**

(58) **Field of Classification Search**  
USPC ..... D10/83-85; 73/706, 715, 716, 717, 73/723, 725, 756, 721, 727, 754; 257/415, 257/417, 692, E21.506, E29.324, E21.002, 257/E21.499, E23.004, E23.066, E29.141; 439/51, 617

See application file for complete search history.

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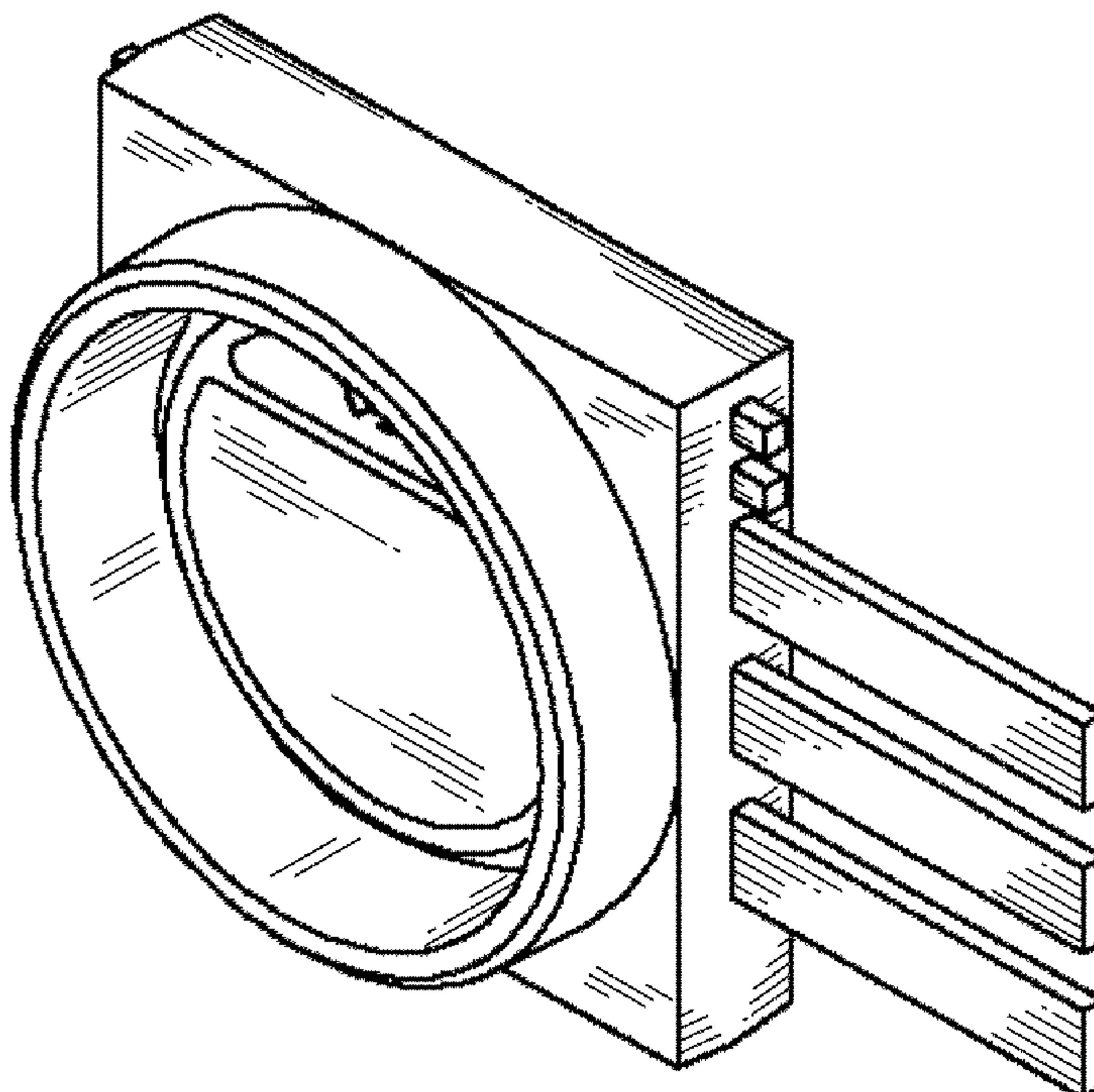
(57) **CLAIM**

The ornamental design for a pressure sensor package, as shown and described.

**DESCRIPTION**

FIG. 1 is a front, top and right side perspective of the pressure sensor package showing our new design; FIG. 2 is a front elevational view thereof; FIG. 3 is a rear elevational view thereof; FIG. 4 is a right side elevational view thereof; FIG. 5 is a left side elevational view thereof; FIG. 6 is a top plan view thereof; and, FIG. 7 is a bottom plan view thereof.

**1 Claim, 4 Drawing Sheets**





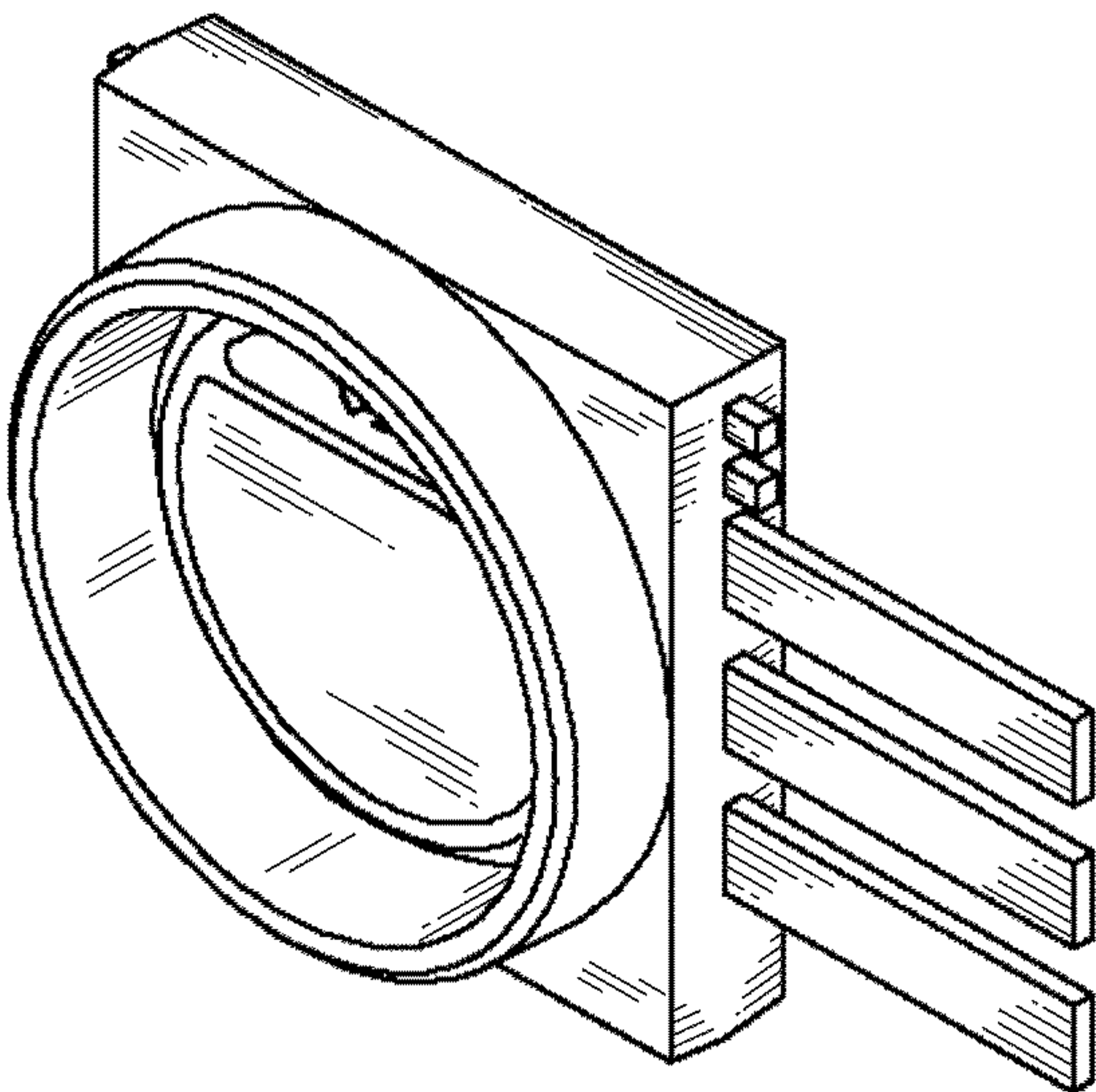


FIG.1

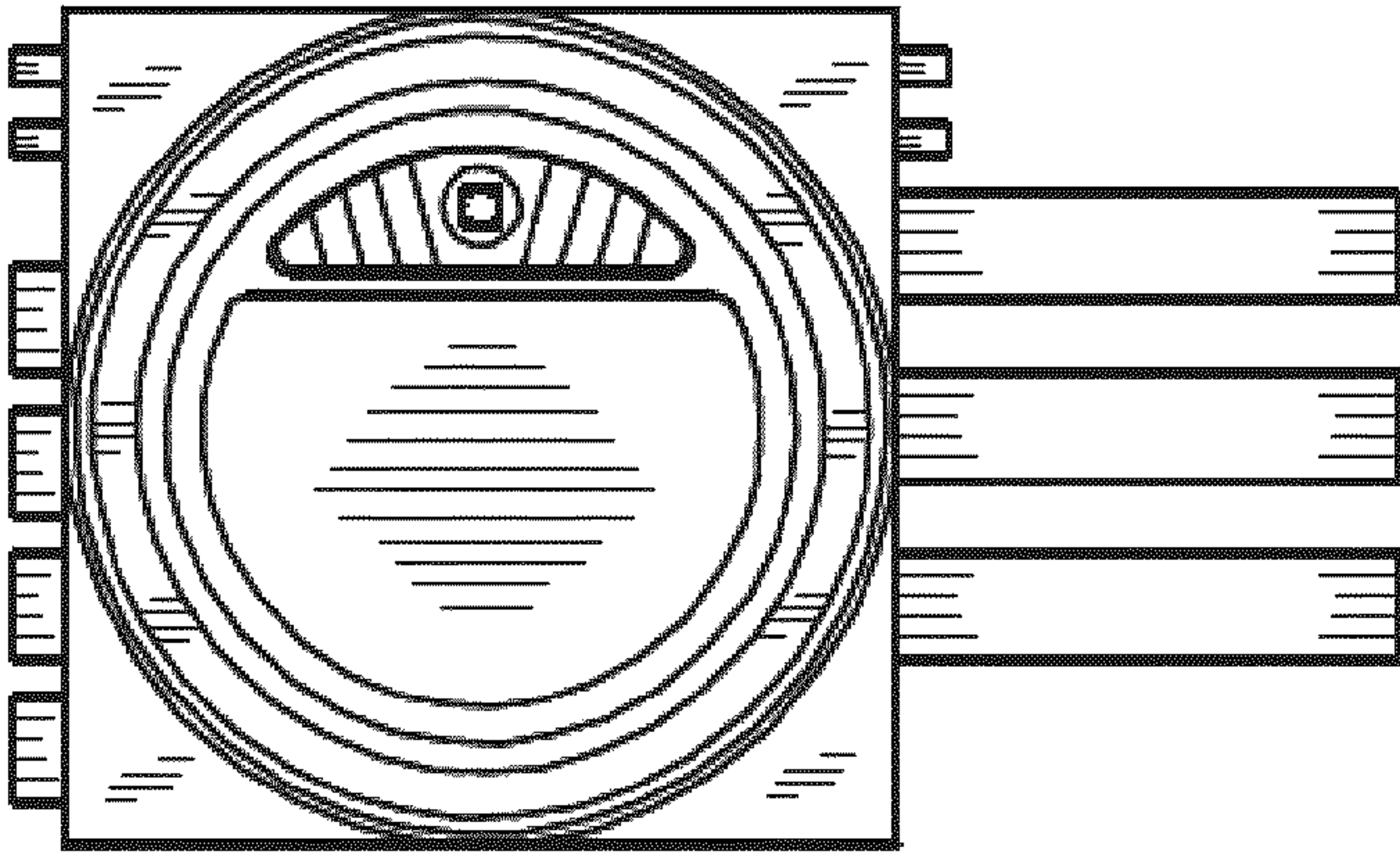


FIG.2



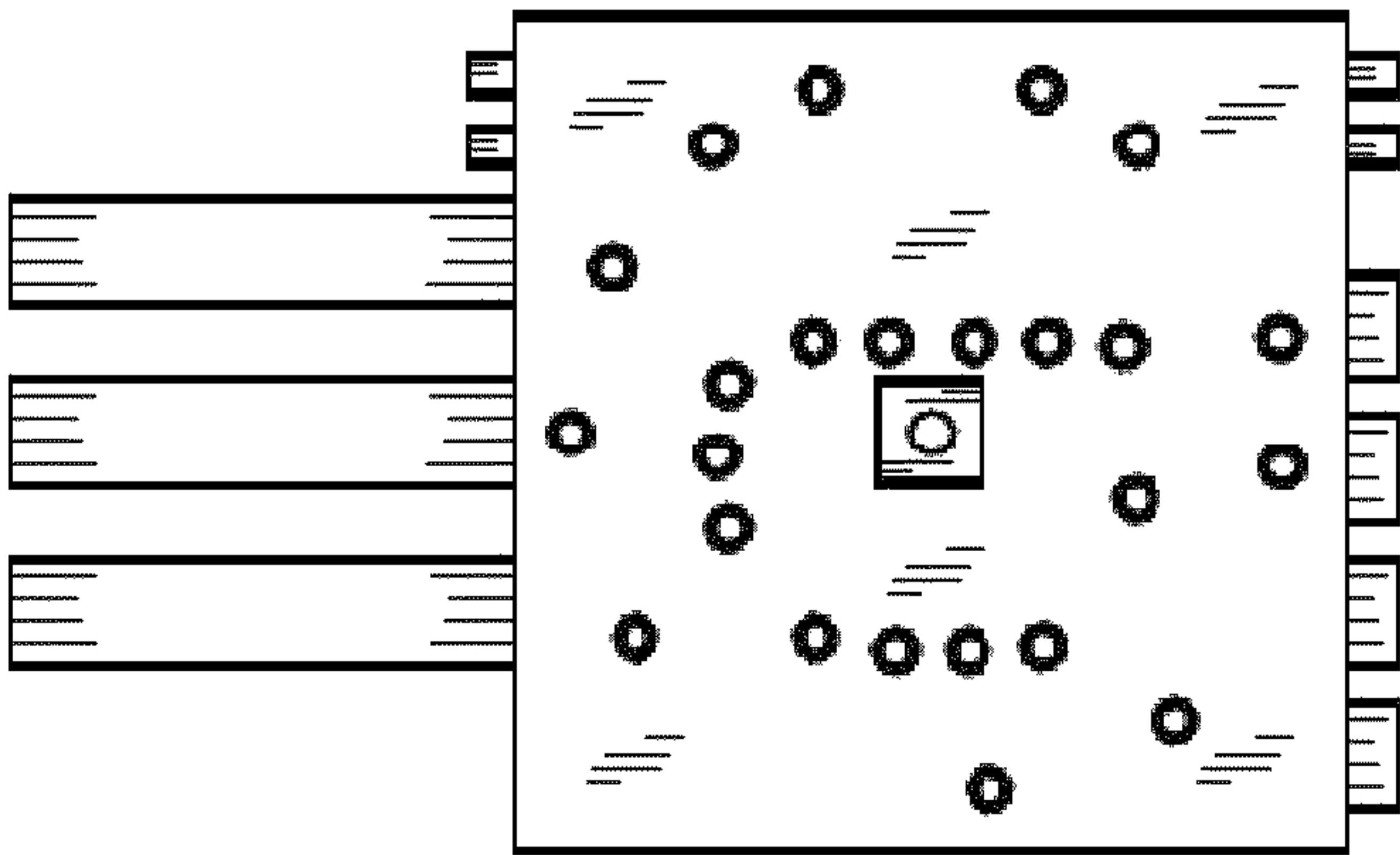


FIG.3

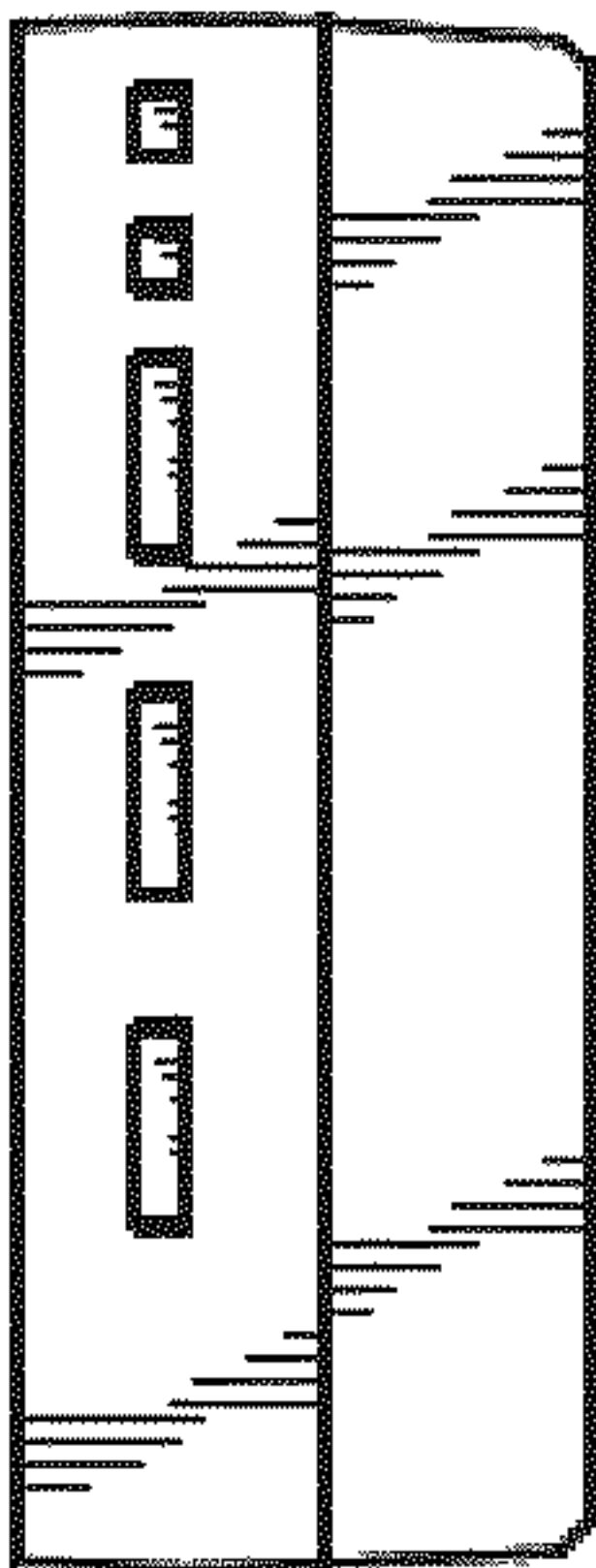


FIG.4



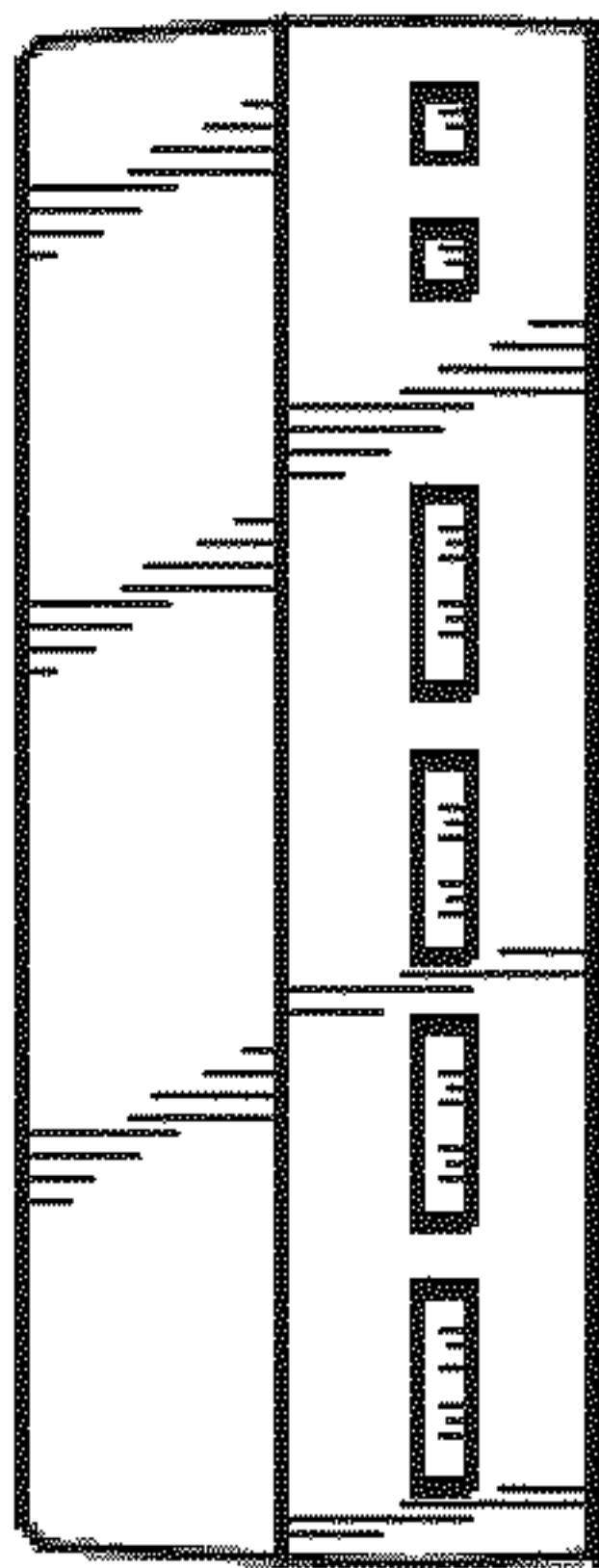


FIG.5

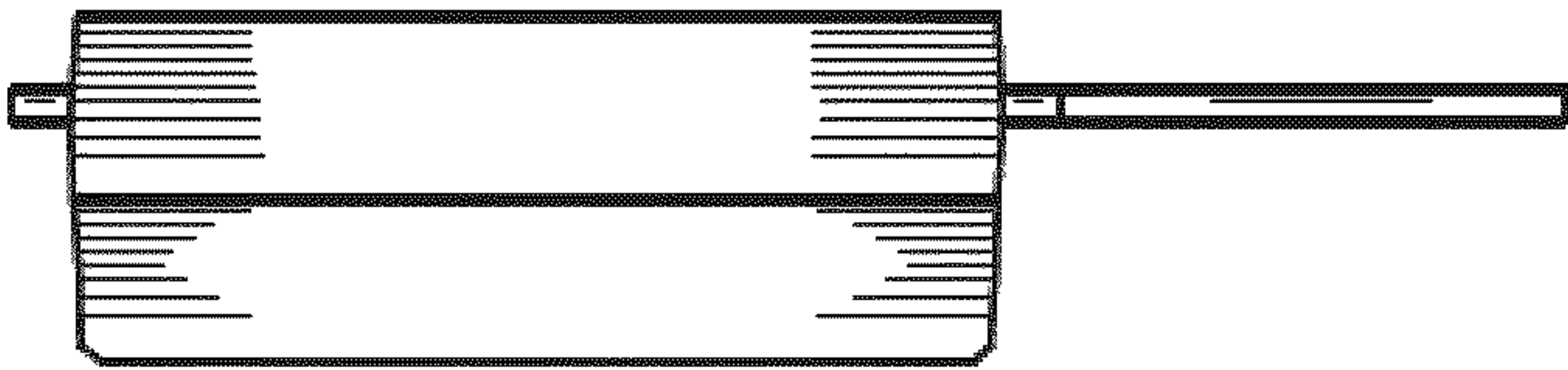


FIG.6



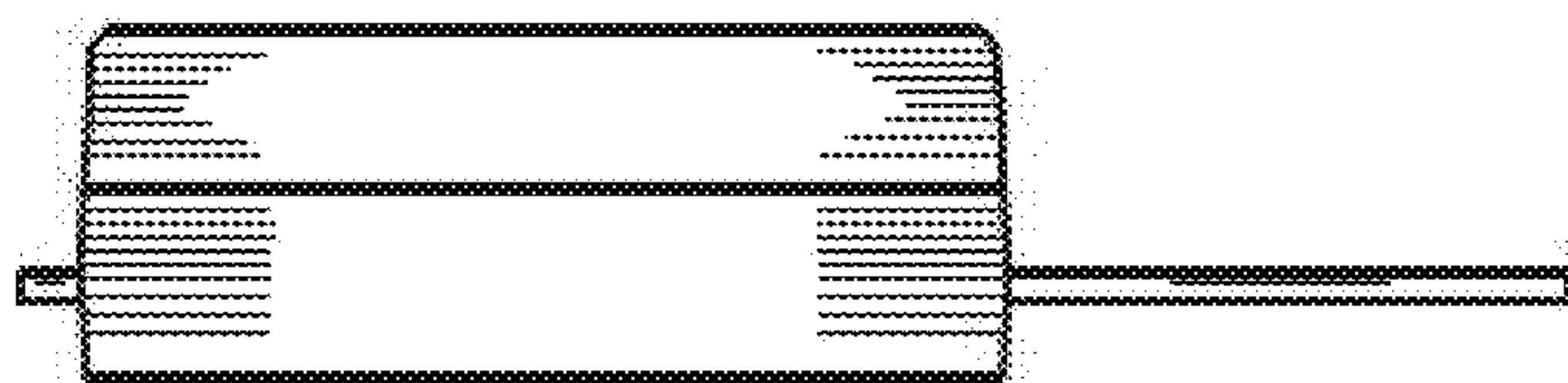


FIG.7